# **Single 2-Input AND Gate**

The NL17SZ08 is a single 2-input AND Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive. They should be used wherever the need for higher speed and drive are needed.

#### **Features**

- Tiny SOT-353 and SOT-553 Packages
- 2.7 ns T<sub>PD</sub> at 5.0 V (typ)
- Source/Sink 24 mA at 3.0 V
- Overvoltage Tolerant Inputs
- Pin For Pin with NC7SZ08P5X, TC7SZ08FU and TC7SZ08AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Pb-Free Packages are Available

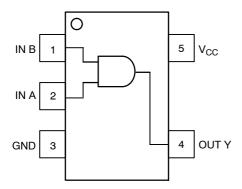


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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MARKING DIAGRAMS



SC-70/SC-88A/SOT-353 DF SUFFIX CASE 419A





SOT-553 XV5 SUFFIX CASE 463B



L2 = Device Code M = Date Code\*

A = Assembly Location

Y = Year

W = Work Week ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **PIN ASSIGNMENT**

Pin	Function
1	In B
2	In A
3	GND
4	Out Y
5	V <sub>CC</sub>

#### **FUNCTION TABLE**

Inp	Output Y = AB	
Α	В	Υ
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parame	eter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5  to  +7.0	V
V <sub>OUT</sub>	DC Output Voltage	$-0.5$ to $V_{CC}$ $+0.5$	V	
I <sub>IK</sub>	DC Input Diode Current		-50	mA
I <sub>OK</sub>	DC Output Diode Current		-50	mA
I <sub>OUT</sub>	DC Output Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	± 100	mA	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10	260	°C	
$T_J$	Junction Temperature Under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	2 kV 400 V N/A	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
   Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	I Parameter			Max	Unit
V <sub>CC</sub>	DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	DC Input Voltage			5.5	V
V <sub>OUT</sub>	DC Output Voltage		0	V <sub>CC</sub> + 0.5	V
T <sub>A</sub>	Operating Temperature Range		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = V <sub>CC</sub> =	3.0 V ± 0.3 V 5.0 V ± 0.5 V	0	100 20	ns/V

### DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>	T	A = 25°	С	-40°C ≤	<b>T</b> <sub>A</sub> ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$I_{OH} = 100 \mu A$ $I_{OH} = -3 \text{ mA}$ $I_{OH} = -8 \text{ mA}$ $I_{OH} = -12 \text{ mA}$ $I_{OH} = -16 \text{ mA}$ $I_{OH} = -24 \text{ mA}$ $I_{OH} = -32 \text{ mA}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		<b>&gt;</b>
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>OH</sub>	$I_{OL} = 100 \ \mu\text{A}$ $I_{OL} = 3 \ \text{mA}$ $I_{OL} = 8 \ \text{mA}$ $I_{OL} = 12 \ \text{mA}$ $I_{OL} = 16 \ \text{mA}$ $I_{OL} = 24 \ \text{mA}$ $I_{OL} = 32 \ \text{mA}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55		0.1 0.24 0.3 0.4 0.4 0.55	<b>V</b>
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	0 to 5.5			± 0.1		±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			1		10	μΑ

## AC ELECTRICAL CHARACTERISTICS $t_{R} = t_{F} = 3.0 \text{ ns}$

			V <sub>CC</sub>	T <sub>A</sub> = 25°C		$_{A} = 25^{\circ}C$ $-40^{\circ}C \leq T_{A} \leq 85^{\circ}C$		$\Gamma_{A} \leq 85^{\circ}C$	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	$R_L = 1 \text{ M}\Omega$ , $C_L = 15 \text{ pF}$	1.65	2.0	6.3	12	2.0	12.7	ns
t <sub>PHL</sub>	(Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	1.8	2.0	6.2	10	2.0	10.5	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	0.8	3.4	7.0	0.8	7.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	$3.3 \pm 0.3$	0.5	2.6	4.7	0.5	5.0	
		$R_L = 500 \Omega, C_L = 50 pF$		1.5	3.3	5.2	1.5	5.5	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	5.0 ± 0.5	0.5	2.2	4.1	0.5	4.4	
		$R_L = 500 \Omega, C_L = 50 pF$		8.0	2.7	4.5	8.0	4.8	

### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	>4.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF
	(Note 5)	10 MHz, $V_{CC}$ = 5.5 V, $V_{I}$ = 0 V or $V_{CC}$	30	

<sup>5.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

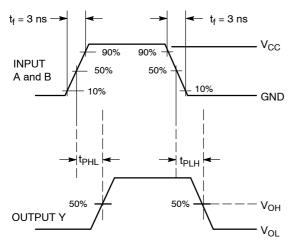
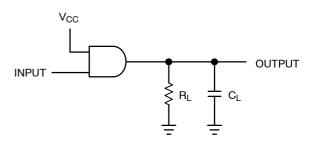


Figure 3. Switching Waveform



A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

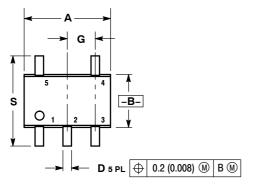
### **DEVICE ORDERING INFORMATION**

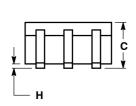
Device Order Number	Package Type	Tape and Reel Size <sup>†</sup>
NL17SZ08DFT2	SC70-5/SC-88A/SOT-353	4000 / Tape & Reel
NL17SZ08DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	4000 / Tape & Reel
NL17SZ08XV5T2	SOT-553*	4000 / Tape & Reel
NL17SZ08XV5T2G	SOT-553*	4000 / Tape & Reel

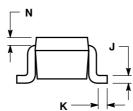
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*All Devices in Package SOT553 are Inherently Pb-Free.

### **PACKAGE DIMENSIONS**

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J** 







#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

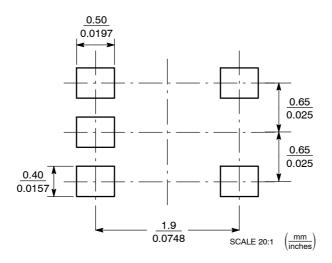
  2. CONTROLLING DIMENSION: INCH.

  3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65	BSC	
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20 REF		
S	0.079	0.087	2.00	2.20	

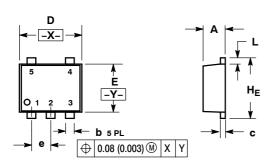
### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SOT-553 XV5 SUFFIX 5-LEAD PACKAGE CASE 463B-01 ISSUE B



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
  3. MAXIMUM LEAD THICKNESS INCLUDES
  LEAD FINISH THICKNESS. MINIMUM LEAD
  THICKNESS IS THE MINIMUM THICKNESS
  OF BASE MATERIAL.

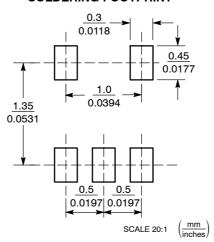
	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
е		0.50 BSC		0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 1: PIN 1. BASE 1 2. EMITTER 1/2

STYLE 2: PIN 1. CATI 2 2. ANO 3. CATI

3. BASE 2 4. COLLECTOR 2 5. COLLECTOR 1 PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. CATHODE

#### **SOLDERING FOOTPRINT\***



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